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**PRODUCT/PROCESS CHANGE NOTIFICATION**  
Generic Copy

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**21-SEP-2001**

**SUBJECT: ON Semiconductor Product/Process Change Notification #11765**

**TITLE: Small Signal Wafer Process Conversion Addendum**

**EFFECTIVE DATE: 21-Nov-2001**

**AFFECTED CHANGE CATEGORY: Wafer Process, Die Shrink, and Design Change**

**AFFECTED PRODUCT DIVISION: Bipolar Discretes Products**

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or Monica Griffin <R39205@onsemi.com >

**SAMPLES:** Contact Below

Contact your local ON Semiconductor Sales Office or Monica Griffin <R39205@onsemi.com>

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact Sales Office or Monica Griffin <R39205@onsemi.com>

**DISCLAIMER:**

Initial Product/Process Change Notification (IPCN) - First Notification distributed to customers.  
Distributed at least 120 days from the effective date of the change.

Final Product/Process Change Notification (FPCN) - Final Notification completing the notification process. Distributed at least 60 days from the effective date of the change. ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

**DESCRIPTION AND PURPOSE:**

This process change notification is an addendum to PCN 10149 that was issued last year, to include additional parts. These parts share the same process as parts already converted. This is to advise customers of the conversion of ON Semiconductor's Small Signal family from 12um to 6um linewidth wafer process. The change methodology will result in die shrink. The devices will be guaranteed to meet all existing specs.

**QUALIFICATION PLAN:**

See Reliability Data.



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**RELIABILITY DATA SUMMARY:**

- 1)Qual Vehicle: BC857BLT1
- 2) Test Results

Test	Item	Results
		-----Sample Size/ Rejects
HTRB(@Ta=150 deg C w/bias	1000 hours	231/0
IOL Tj=100 degC, Ta=25 deg C	1000 hours	231/ 0
Temp Cycle Ta=65/150 deg C	1000 cycles	231/ 0
Autoclave (15PSI,121degc RH=100%)	192 hours	231/ 0

**ELECTRICAL CHARACTERISTIC SUMMARY:**

Electrical characterization indicates parameteric distribution remains unchanged.  
Data available on request.

**CHANGED PART IDENTIFICATION:**

No physical change to the external portion of the product. Affected date codes may be 0148 or later for TO92 and a date code of C or later for SOT23.

**RELATED NOTIFICATIONS:**

#10149 - SMALL SIGNAL WAFER PROCESS CONVERSION

**AFFECTED DEVICE LIST (WITHOUT SPECIALS)**

**PART**

- 2N3903
- 2N3903RLRM
- 2N3904
- 2N3904RL1
- 2N3904RLRA
- 2N3904RLRE
- 2N3904RLRM
- 2N3904RLRP
- 2N3904ZL1
- 2N4123
- 2N4123RLRA
- 2N4123RLRM
- LC945Q
- MMBT6429LT1
- MPS8598RLRA
- MPS8599RLRA
- MPS9634C
- SMBT1000LT1
- SMMBT6429LT1
- SMMBT6429LT3